

Clock Buffer/Driver

Features

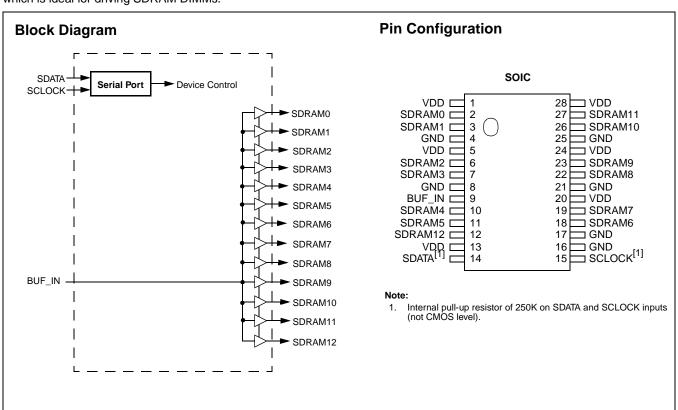
- Thirteen skew-controlled CMOS clock outputs (SDRAM0:12)
- Supports three SDRAM DIMMs
- Ideal for high-performance systems designed around Intel's latest chip set
- · SMBus serial configuration interface
- · Clock Skew between any two outputs is less than 250 ps
- 1- to 5-ns propagation delay
- DC to 133-MHz operation
- Single 3.3V supply voltage
- Low power CMOS design packaged in a 28-pin, 300-mil SOIC (Small Outline Integrated Circuit), 28-pin, 173-mil (Thin Shrink Small Outline Package), and 28-pin, 209-mil SSOP (Small Shrink Outline Package)

Overview

The Cypress W40S11-23 is a low-voltage, thirteen-output clock buffer. Output buffer impedance is approximately 15Ω, which is ideal for driving SDRAM DIMMs.

Key Specifications

Supply Voltages:	$V_{DD} = 3.3V \pm 5\%$
Operating Temperature:	0°C to +70°C
Input Threshold:	1.5V typical
Maximum Input Voltage:	V _{DD} + 0.5V
Input Frequency:	0 to 133 MHz
BUF_IN to SDRAM0:12 Propaga	ation Delay: 1.0 to 5.0 ns
Output Edge Rate:	≥1.5 V/ns
Output Clock Skew:	±250 ps
Output Duty Cycle:	45/55% worst case
Output Impedance:	15 Ω typical
Output Type:	CMOS rail-to-rail





Pin Definitions

Pin Name	Pin No.	Pin Type	Pin Description
SDRAM0:12	2, 3, 6, 7, 10, 11, 18, 19, 22, 23, 26, 27, 12	0	SDRAM Outputs: Provides buffered copy of BUF_IN. The propagation delay from a rising input edge to a rising output edge is 1 to 5 ns. All outputs are skew controlled to within ± 250 ps of each other.
BUF_IN	9	I	Clock Input: This clock input has an input threshold voltage of 1.5V (typ).
SDATA	14	I/O	SMBus Data Input: Data should be presented to this input as described in the SMBus section of this data sheet. Internal 250-k Ω pull-up resistor.
SCLOCK	15	I	SMBus Clock Input: The SMBus data clock should be presented to this input as described in the SMBus section of this data sheet. Internal 250-kΩ pull-up resistor.
VDD	1, 5, 13, 20, 24, 28	Р	Power Connection: Power supply for core logic and output buffers. Connected to 3.3V supply.
GND	4, 8, 16, 17, 21, 25	G	Ground Connection: Connect all ground pins to the common system ground plane.

Functional Description

Output Drivers

The W40S11-23 output buffers are CMOS type which deliver a rail-to-rail (GND to $\rm V_{\rm DD}$) output voltage swing into a nominal

capacitive load. Thus output signaling is both TTL and CMOS level compatible. Nominal output buffer impedance is 15Ω

Operation

Data is written to the W40S11-23 in ten bytes of eight bits each. Bytes are written in the order shown in *Table 1*.

Table 1. Byte Writing Sequence

Byte Sequence	Byte Name	Bit Sequence	Byte Description
1	Slave Address	11010010	Commands the W40S11-23 to accept the bits in Data Bytes 0–6 for internal register configuration. Since other devices may exist on the same common serial data bus, it is necessary to have a specific slave address for each potential receiver. The slave receiver address for the W40S11-23 is 11010010. Register setting will not be made if the Slave Address is not correct (or is for an alternate slave receiver).
2	Command Code	Don't Care	Unused by the W40S11-23, bit values are ignored (Don't Care). This byte must be included in the data write sequence to maintain proper byte allocation. The Command Code Byte is part of the standard serial communication protocol and may be used when writing to another addressed slave receiver on the serial data bus.
3	Byte Count	Don't Care	Unused by the W40S11-23, bit values are ignored (Don't Care). This byte must be included in the data write sequence to maintain proper byte allocation. The Byte Count Byte is part of the standard serial communication protocol and may be used when writing to another addressed slave receiver on the serial data bus.
4	Data Byte 0	Refer to Table 2	The data bits in these bytes set internal W40S11-23 registers that control
5	Data Byte 1		device operation. The data bits are only accepted when the Address Byte bit sequence is 11010010, as noted above. For description of bit control
6	Data Byte 2		functions refer to Table 2.
7	Data Byte 3	Don't Care	Refer to Cypress Frequency Timing Generators.
8	Data Byte 4		
9	Data Byte 5		
10	Data Byte 6		



Writing Data Bytes

Table 2 gives the bit formats for registers located in Data Bytes 0-6.

Each bit in the data bytes control a particular device function. Bits are written MSB (most significant bit) first, which is bit 7.

Table 2. Data Bytes 0–2 Serial Configuration ${\rm Map}^{[2]}$

	Affe	cted Pin		Bit C	ontrol
Bit(s)	Pin No.	Pin Name	Control Function	0	1
Data Byte 0	SDRAM Acti	ve/Inactive Regi	ster (1 = Enable, 0 = Disable)		
7	11	SDRAM5	Clock Output Disable	Low	Active
6	10	SDRAM4	Clock Output Disable	Low	Active
5	N/A	Reserved	(Reserved)	-	-
4	N/A	Reserved	(Reserved)	-	-
3	7	SDRAM3	Clock Output Disable	Low	Active
2	6	SDRAM2	Clock Output Disable	Low	Active
1	3	SDRAM1	Clock Output Disable	Low	Active
0	2	SDRAM0	Clock Output Disable	Low	Active
Data Byte 1	SDRAM Acti	ve/Inactive Regi	ster (1 = Enable, 0 = Disable)		
7	27	SDRAM11	Clock Output Disable	Low	Active
6	26	SDRAM10	Clock Output Disable	Low	Active
5	23	SDRAM9	Clock Output Disable	Low	Active
4	22	SDRAM8	Clock Output Disable	Low	Active
3	N/A	Reserved	(Reserved)	-	-
2	N/A	Reserved	(Reserved)	-	-
1	19	SDRAM7	Clock Output Disable	Low	Active
0	18	SDRAM6	Clock Output Disable	Low	Active
Data Byte 2	SDRAM Acti	ve/Inactive Regi	ster (1 = Enable, 0 = Disable)		•
7	N/A	Reserved	(Reserved)	-	-
6	12	SDRAM12	Clock Output Disable	Low	Active
5	N/A	Reserved	(Reserved)		
4	N/A	Reserved	(Reserved)		
3	N/A	Reserved	(Reserved)		
2	N/A	Reserved	(Reserved)		
1	N/A	Reserved	(Reserved)		
0	N/A	Reserved	(Reserved)		

Note:

^{2.} At power-up all SDRAM outputs are enabled and active. Program Reserved bits to a "0."



How To Use the Serial Data Interface

Electrical Requirements

Figure 1 illustrates electrical characteristics for the serial interface bus used with the W40S11-23. Devices send data over the bus with an open drain logic output that can (a) pull the bus line LOW, or (b) let the bus default to logic 1. The pull-up resistor on the bus (both clock and data lines) establish a default

logic 1. All bus devices generally have logic inputs to receive data.

Although the W40S11-23 is a receive-only device (no data write-back capability), it does transmit an "acknowledge" data pulse after each byte is received. Thus, the SDATA line can both transmit and receive data.

The pull-up resistor should be sized to meet the rise and fall times specified in AC parameters, taking into consideration total bus line capacitance.

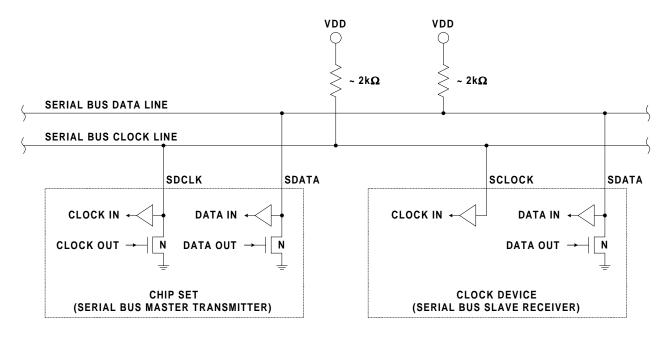


Figure 1. Serial Interface Bus Electrical Characteristics



Signaling Requirements

As shown in *Figure* 2, valid data bits are defined as stable logic 0 or 1 condition on the data line during a clock HIGH (logic 1) pulse. A transitioning data line during a clock HIGH pulse may be interpreted as a start or stop pulse (it will be interpreted as a start or stop pulse if the start/stop timing parameters are met).

A write sequence is initiated by a "start bit" as shown in *Figure* 3. A "stop bit" signifies that a transmission has ended.

As stated previously, the W40S11-23 sends an "acknowledge" pulse after receiving eight data bits in each byte as shown in *Figure 4*.

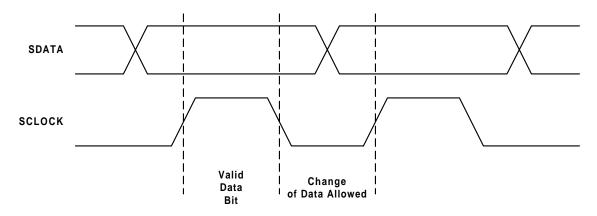


Figure 2. Serial Data Bus Valid Data Bit

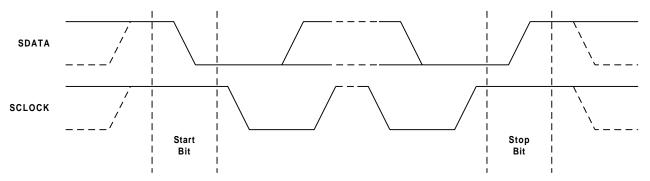


Figure 3. Serial Data Bus Start and Stop Bit



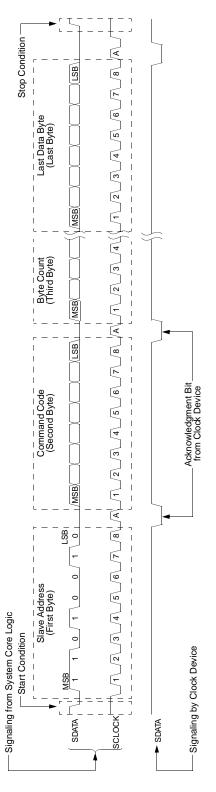


Figure 4. Serial Data Bus Write Sequence

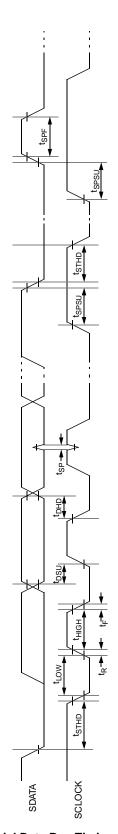


Figure 5. Serial Data Bus Timing Diagram



Absolute Maximum Ratings

Stresses greater than those listed in this table may cause permanent damage to the device. These represent a stress rating only. Operation of the device at these or any other conditions

above those specified in the operating sections of this specification is not implied. Maximum conditions for extended periods may affect reliability.

Parameter	Description	Rating	Unit
V _{DD} , V _{IN}	Voltage on any pin with respect to GND	-0.5 to +7.0	V
T _{STG}	Storage Temperature	-65 to +150	°C
T _A	Operating Temperature	0 to +70	°C
T _B	Ambient Temperature under Bias	-55 to +125	°C

DC Electrical Characteristics: $T_A = 0$ °C to +70°C, $V_{DD} = 3.3V \pm 5\%$

Parameter	Description	Test Condition/Comments	Min.	Тур.	Max.	Unit
I _{DD}	3.3V Supply Current	BUF_IN = 100 MHz			250	mA
Logic Inputs						
V _{IL}	Input Low Voltage		GND-0.3		0.8	V
V _{IH}	Input High Voltage		2.0		V _{DD} +0.5	V
I _{ILEAK}	Input Leakage Current, BUF_IN		- 5		+5	μA
I _{ILEAK}	Input Leakage Current ^[3]		-20		+5	μA
Logic Output	ts (SDRAM0:12)					
V _{OL}	Output Low Voltage	I _{OL} = 1 mA			50	mV
V _{OH}	Output High Voltage	I _{OH} = -1 mA	3.1			V
I _{OL}	Output Low Current	V _{OL} = 1.5V	65	100	160	mA
I _{OH}	Output High Current	V _{OH} = 1.5V	70	110	185	mA
Pin Capacita	nce/Inductance					
C _{IN}	Input Pin Capacitance				5	pF
C _{OUT}	Output Pin Capacitance				6	pF
L _{IN}	Input Pin Inductance				7	nΗ

Note:

^{3.} SDATA and SCLOCK logic pins have 250-k Ω internal pull-up resistors.



AC Electrical Characteristics: $T_A = 0$ °C to +70°C, $V_{DD} = 3.3$ V ±5% (Lump Capacitance Test Load = 30 pF)

Parameter	Description	Test Condition	Min	Тур	Max	Unit
f _{IN}	Input Frequency		0		133	MHz
t _R	Output Rise Edge Rate	Measured from 0.4V to 2.4V	1.5		4.0	V/ns
t _F	Output Fall Edge Rate	Measured from 2.4V to 0.4V	1.5		4.0	V/ns
t _{SR}	Output Skew, Rising Edges				250	ps
t _{SF}	Output Skew, Falling Edges				250	ps
t _{EN}	Output Enable Time		1.0		8.0	ns
t _{DIS}	Output Disable Time		1.0		8.0	ns
t _{PR}	Rising Edge Propagation Delay		1.0		5.0	ns
t _{PF}	Falling Edge Propagation Delay		1.0		5.0	ns
t _D	Duty Cycle	Measured at 1.5V	45		55	%
Z _o	AC Output Impedance			15		Ω
t _{PR}	Rising Edge Propagation Delay		1.0		5.0	ns

Ordering Information

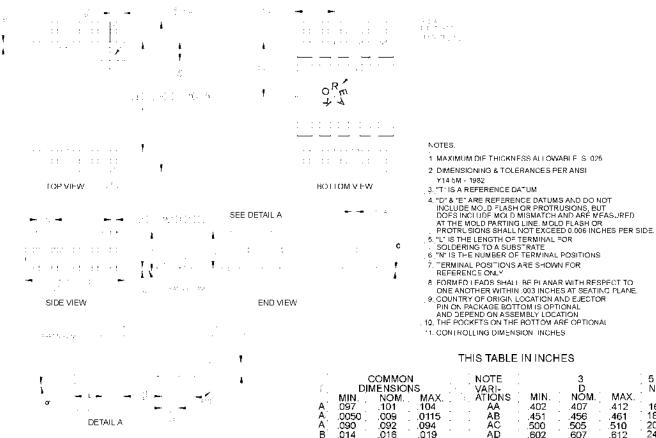
Ordering Code	Freq. Mask Code	Package Name	Package Type
W40S11	-23	G	28-pin SOIC (300 mils)
		X	28-pin TSSOP (173 mil)
		Н	28-pin SSOP (209 mil)

Document #: 38-00793-*B



Package Diagrams

28-Pin Small Outline Integrated Circuit (SOIC, 0.300 inch)



		COMMO	V		NOTE		3		5
í.	DI	MENSIO	NS		VARI-		D		N
	MIN.	NOM.	MAX.		ATIONS	MIN.	NOM.	MAX.	
A.	.097	.101	.104		. AA	.402	.407	.412	16
Α.	.0050	.009	.0115		, AB	. 451	456	461	18
Α.	.090	.092	094		. AC	.500	505	.510	. 20
В.	.014	.016	019		, ĄD	.602	607	.612	24
C,	.0091	.010	.0125] AE	701	706	711	28
D,		VARIATION		. 3					
Ε,	.292	.296	.299						
e.		.050 BSC							
Η,	400	.406	.410						
h,	010	.013	.016						
L,	.024	.032	.040						
Ŋ,		VARIATION		5					
	O°	5°	8°		_		_		_
X	.085	.093	.100						

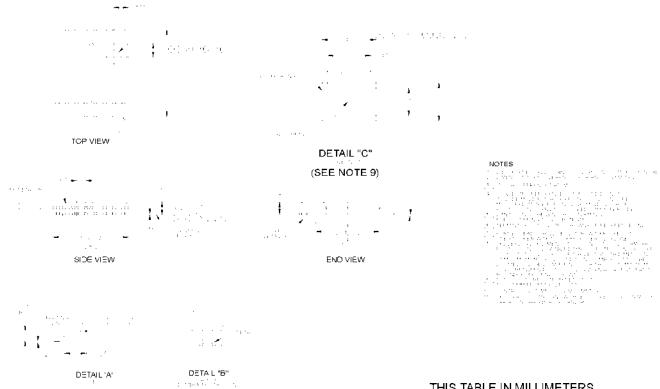
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	COMMON DIMENSIONS				NOTE VARI-		3 D		5 N
	MIN.	NOM.	MAX		ATIONS	MIN.	NOM.	MAX.	
Α.	2.46	2.56	2.64		. AA	10.21	10.34	10.46	. 16
Α.	0.127	0.22	0.29		, AB	11.46	11.58	. 11.71	. 18
Α.	2.29	2.34	2.39		: AC	12.70	12.83	12.95	. 20,
В.	0.35	0.41	0.48		. AD	15.29	15.42	15.54	. 24
C.	0.23	0.25	0.32		AE	17.81	17.93	18.06	_ 28
D.		VARIATION		3					
E,	7.42	7.52	7.59						
e		1.27 BSC							
Η.	10.16	10.31	10.41						
h)	0.25	0.33	0.41						
L.	0.61	0.81	1.02						
Ŋ,		VARIATION		5					
	0°	5°	8°						
X	2.16	2.36	2.54	•	•		-		



Package Diagrams (continued)

28-Pin Thin Shrink Small Outline Package (TSSOP, 173-mil)



THIS TABLE IN MILLIMETERS

v.	DIMENSIONS				NOTE VARI-		4 D		6 N
	MIN.	NOM.	MAX.	. i.	ATIONS	MIN.	NOM.	MAX.	
A			1.10		AA	2.90	3 00	3.10	8
· A	0.05	D 10	0.15		AB	4.90	5 00	5.10	14
Α.	0.85	0.90	0.95		AC .	4.90	5 00	5.10	16
į bį	0.19		0.30	8	AD	6.40	650	6.60	20
b1	0.19	0.22	0.25		. AE	7.70	7.80	7.90	24
	0.090		0.20		AF	9.60	970	9.80	28
	0.090	0.127	0.135						
D.	SEE	VARIATION	is	4					
E.	4.30	4.40	4.50	4					
e e		0.65 BSC							
. H.	6 25	6.40	5.50						
L	0.50	0.80	0.70	- 5					
N SEE VARIATIONS			6						
1.	O°	. 4°	8°						

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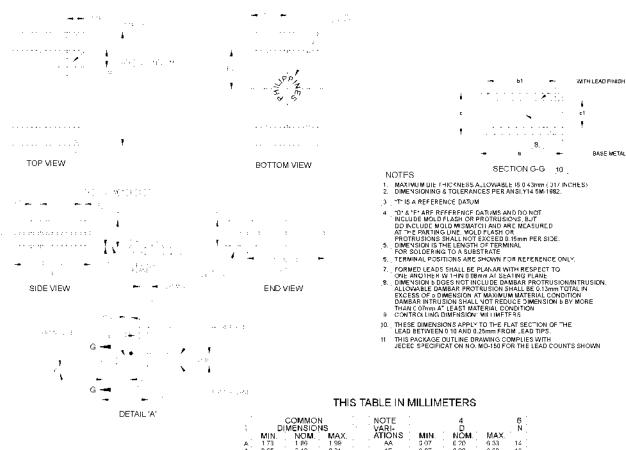
	COMMON				NOTE		4		6
Ϊ.	DIMENSIONS				VARI-		D.		N
	MIN.	NOM.	MAX.		ATIONS	MIN.	NOM.	MAX.	
A			.0433		AA '	114	.118	.122	8
A	002	.004	.006	•	. AB	193	197	201	14
A.	.0335	.0354	.0374	•	. AC .	.193	.197	.201	16
b i	.0075		.0118	8	AD .	252	.256	.260	20
b1	0075	0087	0098		. AE .	303	307	311	24
e i	.0035		.0079		AF .	.378	.382	.386	28
c1	.0035	. 005G .	.0053		•				
D.	SEE	VARIATION	S	4					
E.	169	.173	.177	4					
e i		.0256 BSC			•				
H.	.246	.252	.256		•				
L.	020	.024	.028	5					
N	SEE	VARIATION	S	- 6	•				
17	٥°	. 4° .	8°						

VARIATION AF IS DESIGNED BUT NOT TOOLED



Package Diagrams (continued)

28-Pin Small Shrink Outline Package (SSOP, 209 mils)



	COMMON DIMENSIONS				NOTE		4		6			
1					VARI-		Ď		N '			
	MIN.	NOM.	MAX.		ATIONS	MIN.	NOM.	MAX.				
Α.	1.73	1.86	1.99		.AA	9.07	E 20	6.33	14			
A	0.05	0.13	0.21		AFI	6.07	6.20	6.33	18			
Α.	1.68	1.73	1.78		AC	7.07	7.20	7.33	20			
ь.	0.25		0.38	8.10	ALC	8.07	6.20	8 33	24			
b1	0.25	0.20	D 33	10	ÆΕ	10.07	10 20	10.33	2B			
e.	0.09		0.20	10	. Al	10.07	10 20	10.33	39			
o1 .	0.09	0.15	0.16	10					•			
D.	SEE VARIATIONS			· 4								
E.	5.23	5 30	5.38	· 4								
ė		0.65 BSC										
н.	7.69	7.80	7.90						MADIATION AT			
L.	0.63	0.75	0.95	. 5					VARIATION AF			
L1	1.25 REF						IC F	SECION	VED BUT NOT TOOLE	· D		
N.	SEE VARIATIONS			. 8	IS DESIGNED BUT NOT TOOLED							
	O ⁿ	4"	8"									
R.	D 09	0.15										

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· }	DI	COMMON MENSION	is.		NOTE VARI-		4	6 N	
	MIN	NOM.	MAX.		ATIONS	MIN.	NOM.	MAX.	
Α.	069	. 073 .	278		AA	239	. 244	245	. 14
Α	002	005	800		AB	239	244	249	19
A	965	690	.070		AC	.2/8	.284	283	23
b.	010		.015	8.10	AD	.318	.323	328	24
ь1	010	012	.213	12	AE	.397	.402	407	29
c ·	004		.008	10	AF .	.397	.402	407	30
G"	004	006	.006	10					
D.	SEE	VARIATION	S	4					
F.	205	209	212	· 4					
e		.0298 BSC							
11	301	307	311	•					
L.	025	030	037	· 5					
L1		049 REF							
N	SEE	VARIATION		8					
	O°	4"	8°						
R.	004	.006		:					

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